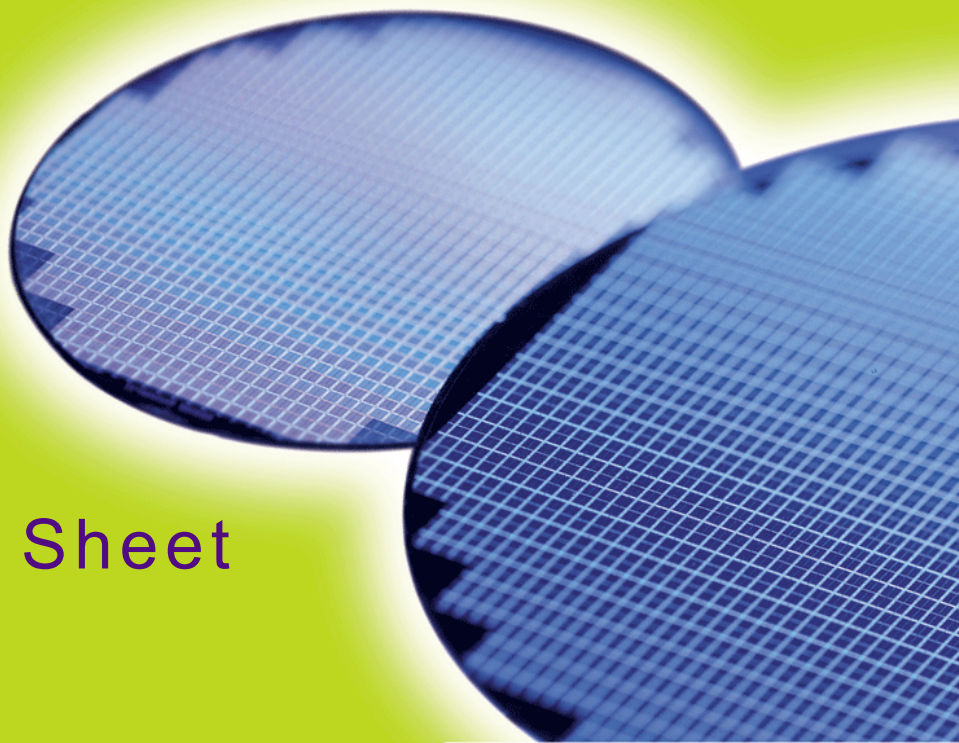


HY[B/I]39S256[40/80/16]0FT(L)
HY[B/I]39S256[40/80/16]0FE(L)
HYB39S256[40/80/16]0FF(L)
HYB39S256407FE

*256-MBit Synchronous DRAM
SDRAM*



Internet Data Sheet

Rev. 1.42

HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM

HY[B/I]39S256[40/80/16]0FT(L), HY[B/I]39S256[40/80/16]0FE(L), HYB39S256[40/80/16]0FF(L), HYB39S256407FE	
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1 Overview

This chapter lists all main features of the product family HYB39S256[400/800/160]F[E/T/F](L) and the ordering information.

1.1 Features

- Fully Synchronous to Positive Clock Edge
- 0 to 70 °C Standard Operating Temperature
- -40 to 85 °C Industrial Operating Temperature
- Four Banks controlled by BA0 & BA1
- Programmable $\overline{\text{CAS}}$ Latency: 2 & 3
- Programmable Wrap Sequence: Sequential or Interleave
- Programmable Burst Length: 1, 2, 4, 8 and full page
- Multiple Burst Read with Single Write Operation
- Automatic and Controlled Precharge Command
- Data Mask for Read / Write control (x4, x8)
- Data Mask for Byte Control (x16)
- Auto Refresh (CBR) and Self Refresh
- Power Down and Clock Suspend Mode
- 8192 refresh cycles / 64 ms (7.8 μs)
- Random Column Address every CLK (1-N Rule)
- Single 3.3 V $\pm$ 0.3 V Power Supply
- LVTTTL Interface versions
- Packages:
 - P(G)–TSOPII–54 (400mil width)
 - PG–TFBGA–54

TABLE 1
Performance

Product Type Speed Code			–6	–7	Unit
Speed Grade			PC166–333	PC133–222	—
Max. Clock Frequency	@CL3	f_{CK3}	166	143	MHz
		t_{CK3}	6	7	ns
		t_{AC3}	5.4	5.4	ns
	@CL2	t_{CK2}	7.5	7.5	ns
		t_{AC2}	5.4	5.4	ns

HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM

1.2 Description

The HYB39S256[400/800/160]F[E/T/F](L) are four bank Synchronous DRAMs organized as 4 banks x 16 MBit x4, 4 banks x 8 MBit x8 and 4 banks x 4 Mbit x16 respectively. These synchronous devices achieve high speed data transfer rates for $\overline{\text{CAS}}$ latencies by employing a chip architecture that prefetches multiple bits and then synchronizes the output data to a system clock. The chip is fabricated with Qimonda's advanced 0.11- μm 256-MBit DRAM process technology.

The device is designed to comply with all industry standards set for synchronous DRAM products, both electrically and mechanically. All of the control, address, data input and output circuits are synchronized with the positive edge of an externally supplied clock.

Operating the four memory banks in an interleave fashion allows random access operation to occur at a higher rate than is possible with standard DRAMs. A sequential and gapless data rate is possible depending on burst length, $\overline{\text{CAS}}$ latency and speed grade of the device.

Auto Refresh (CBR) and Self Refresh operation are supported. These devices operate with a single 3.3 V $\pm$ 0.3 V power supply. All 256-Mbit components are available in P(G)-TSOPII-54 and PG-TFBGA-54 packages.

TABLE 2
Ordering Information for RoHS Compliant Products

Product Type	Speed Grade	Description	Package	Note
Standard Operating Temperature				
HYB39S256407FE-7	PC133-222	143MHz 64M x 4 SDRAM	PG-TFBGA-54	1) 
HYB39S256400FF-7			PG-TFBGA-54	
HYB39S256400FE-7			PG-TSOPII-54	
HYB39S256400FFL-7			PG-TFBGA-54	
HYB39S256400FEL-7			PG-TSOPII-54	
HYB39S256800FF-7		143MHz 32M x 8 SDRAM	PG-TFBGA-54	
HYB39S256800FE-7			PG-TSOPII-54	
HYB39S256800FFL-7			PG-TFBGA-54	
HYB39S256800FEL-7			PG-TSOPII-54	
HYB39S256160FF-7		143MHz 16M x 16 SDRAM	PG-TFBGA-54	
HYB39S256160FE-7			PG-TSOPII-54	
HYB39S256160FFL-7			PG-TFBGA-54	
HYB39S256160FEL-7			PG-TSOPII-54	
HYB39S256160FF-6		166MHz 16M x 16 SDRAM	PG-TFBGA-54	
HYB39S256160FE-6			PG-TSOPII-54	
HYB39S256160FFL-6			PG-TFBGA-54	
HYB39S256160FEL-6			PG-TSOPII-54	
Industrial Operating Temperature				
HYI39S256800FE-7	PC166-333	143MHz 32M x 8 SDRAM	PG-TSOPII-54	1) 
HYI39S256160FE-7		143MHz 16M x 16 SDRAM		

¹⁾ RoHS Compliant Product: Restriction of the use of certain hazardous substances (RoHS) in electrical and electronic equipment as defined in the directive 2002/95/EC issued by the European Parliament and of the Council of 27 January 2003. These substances include mercury, lead, cadmium, hexavalent chromium, polybrominated biphenyls and polybrominated biphenyl ethers.



HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM

TABLE 3**Ordering Information for Lead-Containing Products**

Product Type	Speed Grade	Description	Package
Standard Operating Temperature			
HYB39S256400FT-7	PC133-222	143MHz 64M x 4 SDRAM	P-TSOPII-54
HYB39S256400FTL-7			
HYB39S256800FT-7		143MHz 32M x 8 SDRAM	
HYB39S256800FTL-7			
HYB39S256160FT-7		143MHz 16M x 16 SDRAM	
HYB39S256160FTL-7			
HYB39S256160FT-6		166MHz 16M x 16 SDRAM	
Industrial Operating Temperature			
HYI39S256800FT-7	PC133-222	143MHz 32M x 8 SDRAM	P-TSOPII-54
HYI39S256160FT-7		143MHz 16M x 16 SDRAM	

Note: For product nomenclature see **Chapter 6** of this data sheet



2 Configuration

This chapter contains the pin configuration table, the TSOP and FBGA package drawing, and the block diagrams for the $\times 4$, $\times 8$, $\times 16$ organization of the SDRAM.

2.1 Pin Description

Listed below are the pin configurations sections for the various signals of the SDRAM.

TABLE 4
Pin Configuration of the SDRAM

Ball No.	Name	Pin Type	Buffer Type	Function
Clock Signals $\times 4/\times 8/\times 16$ Organization				
38, 2F	CLK	I	LVTTTL	Clock Signal CK
37, 3F	CKE	I	LVTTTL	Clock Enable
Control Signals $\times 4/\times 8/\times 16$ Organization				
18, 8F	$\overline{\text{RAS}}$	I	LVTTTL	Row Address Strobe (RAS), Column Address Strobe (CAS), Write Enable (WE)
17, 7F	$\overline{\text{CAS}}$	I	LVTTTL	
16, 9F	$\overline{\text{WE}}$	I	LVTTTL	
19, 9G	$\overline{\text{CS}}$	I	LVTTTL	Chip Select
Address Signals $\times 4/\times 8/\times 16$ Organization				
20, 7G	BA0	I	LVTTTL	Bank Address Signals 1:0
21, 8G	BA1	I	LVTTTL	
23, 7H	A0	I	LVTTTL	Address Signal 12:0, Address Signal 10/Auto precharge
24, 8H	A1	I	LVTTTL	
25, 8J	A2	I	LVTTTL	
26, 7J	A3	I	LVTTTL	
29, 3J	A4	I	LVTTTL	
30, 2J	A5	I	LVTTTL	
31, 3H	A6	I	LVTTTL	
32, 2H	A7	I	LVTTTL	
33, 1H	A8	I	LVTTTL	
34, 3G	A9	I	LVTTTL	
22, 9H	A10	I	LVTTTL	
35, 2G	A11	I	LVTTTL	
36, 1G	A12	I	LVTTTL	


HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM

Ball No.	Name	Pin Type	Buffer Type	Function
Data Signals ×4 Organization				
5, 8B	DQ0	I/O	LVTTL	Data Signal Bus 3:0
11, 8D	DQ1	I/O	LVTTL	
44, 2D	DQ2	I/O	LVTTL	
50, 2B	DQ3	I/O	LVTTL	
Data Signals ×8 Organization				
2, 8A	DQ0	I/O	LVTTL	Data Signal Bus 7:0
5, 8B	DQ1	I/O	LVTTL	
8, 8C	DQ2	I/O	LVTTL	
11, 8D	DQ3	I/O	LVTTL	
44, 2D	DQ4	I/O	LVTTL	
47, 2C	DQ5	I/O	LVTTL	
50, 2B	DQ6	I/O	LVTTL	
53, 2A	DQ7	I/O	LVTTL	
Data Signals ×16 Organization				
2, 8A	DQ0	I/O	LVTTL	Data Signal Bus 15:0
4, 9B	DQ1	I/O	LVTTL	
5, 8B	DQ2	I/O	LVTTL	
7, 9C	DQ3	I/O	LVTTL	
8, 8C	DQ4	I/O	LVTTL	
10, 9D	DQ5	I/O	LVTTL	
11, 8D	DQ6	I/O	LVTTL	
13, 9E	DQ7	I/O	LVTTL	
42, 1E	DQ8	I/O	LVTTL	
44, 2D	DQ9	I/O	LVTTL	
45, 1D	DQ10	I/O	LVTTL	
47, 2C	DQ11	I/O	LVTTL	
48, 1C	DQ12	I/O	LVTTL	
50, 2B	DQ13	I/O	LVTTL	
51, 1B	DQ14	I/O	LVTTL	
53, 2A	DQ15	I/O	LVTTL	
Data Mask ×4/×8 Organization				
39, 1F	DQM	I/O	LVTTL	Data Mask
Data Mask ×16 Organization				
39, 1F	UDQM	I/O	LVTTL	Data Mask Upper Byte
15, 8E	LDQM	I/O	LVTTL	Data Mask Lower Byte
Power Supplies ×4/×8/×16 Organization				
3B, 3D, 7A, 7C	V_{DDQ}	PWR	–	Power Supply

HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM

Ball No.	Name	Pin Type	Buffer Type	Function
7E, 9A, 9J	V_{DD}	PWR	–	Power Supply
3A, 3C, 7B, 7D	V_{SSQ}	PWR	–	Power Supply Ground for DQs
1J, 1A, 3E	V_{SS}	PWR	–	Power Supply Ground
Not connected ×4 Organization				
2, 4, 7, 8, 10, 13, 15, 40, 42, 45, 47, 48, 51, 53, 1B, 1C, 1D, 1E, 2A, 2C, 2E, 8A, 8C, 8E, 9B, 9C, 9D, 9E	NC	NC	–	Not connected
Not connected ×8 Organization				
7, 10, 13, 15, 40, 42, 45, 48, 51, 1B, 1C, 1D, 1E, 2E, 8E, 9B, 9C, 9D, 9E	NC	NC	–	Not connected
Not connected ×16 Organization				
40, 2E	NC	NC	–	Not connected

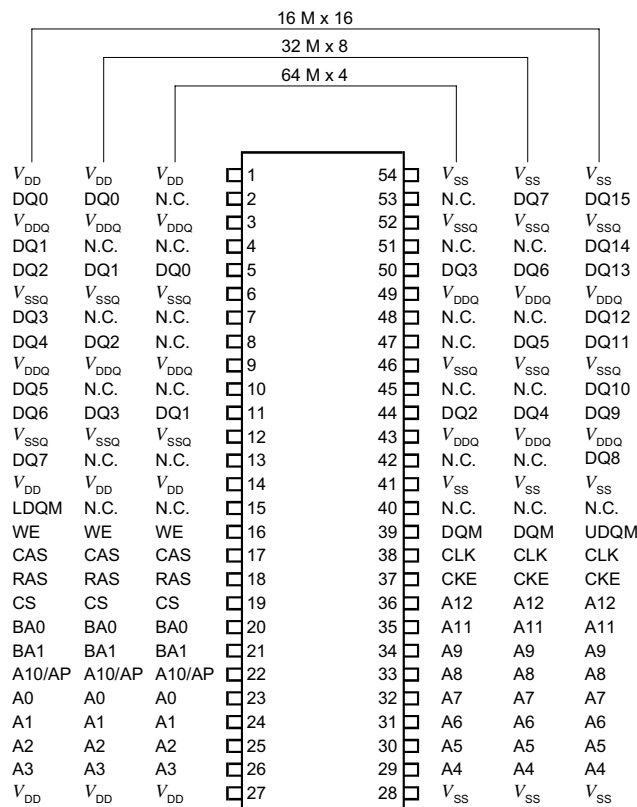


HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM

2.2 Package P(G)–TSOPII–54

Listed below are the pin outs of the TSOP package.

FIGURE 1
Pinouts P(G)–TSOPII–54



TSOPII-54 (400 mil x 875 mil, 0.8 mm pitch)

SPP04126

HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM

2.3 Package PG-TFBGA-54

Listed below are the ball outs of the TFBGA package.

- **Figure 2 “Ballout for ×16 components, TFBGA-54 (top view)” on Page 10**
- **Figure 3 “Ballout for ×8 components, TFBGA-54 (top view)” on Page 11**
- **Figure 4 “Ballout for ×4 components, TFBGA-54 (top view)” on Page 12**

FIGURE 2**Ballout for ×16 components, TFBGA-54 (top view)**

1	2	3	4	5	6	7	8	9
V_{SS}	DQ15	V_{SSQ}		A		V_{DDQ}	DQ0	V_{DD}
DQ14	DQ13	V_{DDQ}		B		V_{SSQ}	DQ2	DQ1
DQ12	DQ11	V_{SSQ}		C		V_{DDQ}	DQ4	DQ3
DQ10	DQ9	V_{DDQ}		D		V_{SSQ}	DQ6	DQ5
DQ8	NC	V_{SS}		E		V_{DD}	LDQM	DQ7
UDQM	CLK	CKE		F		$\overline{\text{CAS}}$	$\overline{\text{RAS}}$	$\overline{\text{WE}}$
A12	A11	A9		G		BA0	BA1	$\overline{\text{CS}}$
A8	A7	A6		H		A0	A1	A10
V_{SS}	A5	A4		J		A3	A2	V_{DD}

MPPD0391

HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM**FIGURE 3**
Ballout for ×8 components, TFBGA-54 (top view)

1	2	3	4	5	6	7	8	9
V_{SS}	DQ7	V_{SSQ}		A		V_{DDQ}	DQ0	V_{DD}
NC	DQ6	V_{DDQ}		B		V_{SSQ}	DQ1	NC
NC	DQ5	V_{SSQ}		C		V_{DDQ}	DQ2	NC
NC	DQ4	V_{DDQ}		D		V_{SSQ}	DQ3	NC
NC	NC	V_{SS}		E		V_{DD}	NC	NC
DQM	CLK	CKE		F		CAS	RAS	$\overline{WE}$
A12	A11	A9		G		BA0	BA1	$\overline{CS}$
A8	A7	A6		H		A0	A1	A10
V_{SS}	A5	A4		J		A3	A2	V_{DD}

MPPD0400

HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM**FIGURE 4****Ballout for ×4 components, TFBGA-54 (top view)**

1	2	3	4	5	6	7	8	9
V_{SS}	NC	V_{SSQ}		A		V_{DDQ}	NC	V_{DD}
NC	DQ3	V_{DDQ}		B		V_{SSQ}	DQ0	NC
NC	NC	V_{SSQ}		C		V_{DDQ}	NC	NC
NC	DQ2	V_{DDQ}		D		V_{SSQ}	DQ1	NC
NC	NC	V_{SS}		E		V_{DD}	NC	NC
DQM	CLK	CKE		F		CAS	RAS	$\overline{WE}$
A12	A11	A9		G		BA0	BA1	$\overline{CS}$
A8	A7	A6		H		A0	A1	A10
V_{SS}	A5	A4		J		A3	A2	V_{DD}

MPPD0410



3 Functional Description

This chapter contains the functional description.

TABLE 5
Truth Table: Operation Command

Operation	Device State	CKE _{n-1} ¹⁾²⁾	CKE _n ¹⁾²⁾	DQM ₁₎₂₎	BA0 BA1 ¹⁾²⁾	AP= A10 ¹⁾²⁾	Addr. 1)2)	$\overline{\text{CS}}^1$ 2)	$\overline{\text{RAS}}^1$ 1)2)	$\overline{\text{CAS}}^1$ 2)	$\overline{\text{WE}}^1$ 1)2)
Bank Active	Idle ³⁾	H	X	X	V	V	V	L	L	H	H
Bank Precharge	Any	H	X	X	V	L	X	L	L	H	L
Precharge All	Any	H	X	X	X	H	X	L	L	H	L
Write	Active ³⁾	H	X	X	V	L	V	L	H	L	L
Write with Auto pre-charge	Active ³⁾	H	X	X	V	H	V	L	H	L	L
Read	Active ³⁾	H	X	X	V	L	V	L	H	L	H
Read with Auto pre-charge	Active ³⁾	H	X	X	V	H	V	L	H	L	H
Mode Register Set	Idle	H	X	X	V	V	V	L	L	L	L
No Operation	Any	H	X	X	X	X	X	L	H	H	H
Burst Stop	Active	H	X	X	X	X	X	L	H	H	L
Device Deselect	Any	H	X	X	X	X	X	H	X	X	X
Auto Refresh	Idle	H	H	X	X	X	X	L	L	L	H
Self Refresh Entry	Idle	H	L	X	X	X	X	L	L	L	H
Self Refresh Exit	Idle (Self Refr.)	L	H	X	X	X	X	H L	X H	X H	X X
Power Down/ Clock Suspend Entry	Active or Idle or Burst	H	L	X	X	X	X	H L	X H	X H	X H
Power Down/ Clock Suspend Exit	Active or Idle or Burst	L	H	X	X	X	X	H L	X H	X H	X H
Data Write/ Output Enable	Active	H	X	L	X	X	X	X	X	X	X
Data Write/ Output Disable	Active	H	X	H	X	X	X	X	X	X	X

1) V = Valid, x = Don't Care, L = Low Level, H = High Level

2) CKE_n signal is input level when commands are provided, CKE_{n-1} signal is input level one clock before the commands are provided.

3) This is the state of the banks designated by BA0, BA1 signals.



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BA1	BA0	A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1	A0
0	0	0	0	0	WBL	TM			CL		BT		BL	
reg. addr					W				W		W		W	

MPBS0001

TABLE 6
Mode Register Definition (BA_{1:0} = 00_B)

Field	Bits	Type	Description
BL	2:0	w	Burst Length <i>Note: All other bit combinations are RESERVED.</i> 000 _B 1 001 _B 2 010 _B 4 011 _B 8 111 _B Full Page (Sequential burst type only)
BT	3		Burst Type 0 _B Sequential 1 _B Interleaved
CL	6:4		CAS Latency Number of full clocks from read command to first data valid window. <i>Note: All other bit combinations are RESERVED.</i> 010 _B 2 011 _B 3
TM	8:7		Test Mode <i>Note: All other bit combinations are RESERVED.</i> 00 _B Mode register set
WBL	9		Write Burst Length 0 _B Burst write 1 _B Single bit write
	12:10		Reserved, set to zero

HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM**TABLE 7**
Burst Length and Sequence

Burst Length	Starting Column Address			Order of Accesses Within a Burst	
	A2	A1	A0	Type=Sequential	Type=Interleaved
2			0	0-1	0-1
			1	1-0	1-0
4		0	0	0-1-2-3	0-1-2-3
		0	1	1-2-3-0	1-0-3-2
		1	0	2-3-0-1	2-3-0-1
		1	1	3-0-1-2	3-2-1-0
8	0	0	0	0-1-2-3-4-5-6-7	0-1-2-3-4-5-6-7
	0	0	1	1-2-3-4-5-6-7-0	1-0-3-2-5-4-7-6
	0	1	0	2-3-4-5-6-7-0-1	2-3-0-1-6-7-4-5
	0	1	1	3-4-5-6-7-0-1-2	3-2-1-0-7-6-5-4
	1	0	0	4-5-6-7-0-1-2-3	4-5-6-7-0-1-2-3
	1	0	1	5-6-7-0-1-2-3-4	5-4-7-6-1-0-3-2
	1	1	0	6-7-0-1-2-3-4-5	6-7-4-5-2-3-0-1
	1	1	1	7-0-1-2-3-4-5-6	7-6-5-4-3-2-1-0
FullPage	n			Cn, Cn+1, Cn+2	not supported

Notes

1. For a burst length of two, A1-Ai selects the two-data-element block; A0 selects the first access within the block.
2. For a burst length of four, A2-Ai selects the four-data-element block; A0-A1 selects the first access within the block.
3. For a burst length of eight, A3-Ai selects the eight-data-element block; A0-A2 selects the first access within the block.
4. Whenever a boundary of the block is reached within a given sequence above, the following access wraps within the block.



4 Electrical Characteristics

This chapter lists the electrical characteristics.

4.1 Operating Conditions

This chapter describes the operating conditions.

TABLE 8
Absolute Maximum Ratings

Parameter	Symbol	Limit Values		Unit	Note/ Test Condition
		Min.	Max.		
Input / Output voltage relative to V_{SS}	V_{IN}, V_{OUT}	- 1.0	+4.6	V	—
Voltage on V_{DD} supply relative to V_{SS}	V_{DD}	- 1.0	+4.6	V	—
Voltage on V_{DDQ} supply relative to V_{SS}	V_{DDQ}	- 1.0	+4.6	V	—
Operating Temperature for HYB...	T_A	0	+70	°C	—
Operating Temperature for HYI...	T_A	- 40	+85	°C	—
Storage temperature range	T_{STG}	-55	+150	°C	—
Power dissipation per SDRAM component	P_D	—	1	W	—
Data out current (short circuit)	I_{OUT}	—	50	mA	—

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.

HY[B/I]39S256[40/80/16][0/7]F[E/T/F](L)
256-MBit Synchronous DRAM**TABLE 9**
DC Characteristics

Parameter	Symbol	Values		Unit	Note ¹⁾ / Test Condition
		Min.	Max.		
Supply Voltage	V_{DD}	3.0	3.6	V	2)
I/O Supply Voltage	V_{DDQ}	3.0	3.6	V	2)
Input high voltage	V_{IH}	2.0	$V_{DDQ} + 0.3$	V	2)3)
Input low voltage	V_{IL}	-0.3	+0.8	V	2)3)
Output high voltage ($I_{OUT} = -4.0$ mA)	V_{OH}	2.4	-	V	2)
Output low voltage ($I_{OUT} = 4.0$ mA)	V_{OL}	-	0.4	V	2)
Input leakage current, any input ($0\text{ V} < V_{IN} < V_{DD}$, all other inputs = 0 V)	I_{IL}	-5	+5	μA	-
Output leakage current (DQs are disabled, $0\text{ V} < V_{OUT} < V_{DDQ}$)	I_{OL}	-5	+5	μA	-

1) $T_A = 0$ to $70\text{ }^\circ\text{C}$ 2) All voltages are referenced to V_{SS} 3) V_{IH} may overshoot to $V_{DDQ} + 2.0$ V for pulse width of < 4 ns with 3.3 V. V_{IL} may undershoot to -2.0 V for pulse width < 4.0 ns with 3.3 V. Pulse width measured at 50% points with amplitude measured peak to DC reference.**TABLE 10**
Input and Output Capacitances

Parameter	Symbol	Values ¹⁾		Unit	Note
		Min.	Max.		
Input Capacitances: CK	C_{I1}	2.5	3.5	pF	2)
Input Capacitance (A0-A12, BA0, BA1, $\overline{\text{RAS}}$, $\overline{\text{CAS}}$, $\overline{\text{WE}}$, $\overline{\text{CS}}$, CKE, DQM)	C_{I2}	2.5	3.8	pF	
Input/Output Capacitance (DQ)	C_{I0}	4.0	6.0	pF	

1) Capacitance values are shown for TSOP-54 packages. Capacitance values for TFBGA packages are lower by 0.5 pF

2) $T_A = 0$ to $70\text{ }^\circ\text{C}$; V_{DD} , $V_{DDQ} = 3.3\text{ V} \pm 0.3\text{ V}$, $f = 1\text{ MHz}$ **TABLE 11**
IDD Conditions

Parameter	Symbol
Operating Current One bank active, Burst length = 1	I_{DD1}
Precharge Standby Current in Power Down Mode	I_{DD2P}
Recharge Standby Current in Non-Power Down Mode	I_{DD2N}
No Operating Current Active state (max. 4 banks)	I_{DD3N}
	I_{DD3P}
Burst Operating Current Read command cycling	I_{DD4}
Auto Refresh Current Auto Refresh command cycling	I_{DD5}

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Parameter	Symbol
Self Refresh Current (standard components) Self Refresh Mode, CKE=0.2V, t_{CK} =infinity	I_{DD6}
Self Refresh Current (low power components) Self Refresh Mode, CKE=0.2V, t_{CK} =infinity	

TABLE 12 **I_{DD} Specifications and Conditions**

Symbol		-6	-7	Unit	Note/ Test Condition ¹⁾²⁾
		Max.			
I_{DD1}	$t_{RC} = t_{RC(min)}, I_O = 0 \text{ mA}$	100	80	mA	3)4)
I_{DD2P}	$\overline{CS} = V_{IH \text{ (min.)}}, CKE \leq V_{IL(max)}$	2	2	mA	2)
I_{DD2N}	$\overline{CS} = V_{IH \text{ (min.)}}, CKE \geq V_{IH(min)}$	26	22	mA	2)
I_{DD3N}	$CS = V_{IH(min)}, CKE \geq V_{IH(min.)}$	40	35	mA	2)
I_{DD3P}	$CS = V_{IH(min)}, CKE \leq V_{IL(max.)}$	5	5	mA	2)
I_{DD4}		65	57	mA	2)3)
I_{DD5}	$t_{RFC} = t_{RFC(min)}$	168	142	mA	5)
	$t_{RFC} = 7.8 \mu\text{S}$	25	25	mA	
I_{DD6}		3	3	mA	Standard components
		1.05	1.05	mA	Low power components ⁶⁾

1) Currents values will be added when available.

2) $T_A = 0$ to $70^\circ C$; $V_{SS} = 0$ V; V_{DD} , $V_{DDQ} = 3.3$ V ± 0.3 V3) These parameters depend on the cycle rate. All values are measured at 166 MHz for -6, at 133 MHz for -7 and -7.5 and at 100 MHz for -8 components with the outputs open. Input signals are changed once during t_{CK} .4) These parameters are measured with continuous data stream during read access and all DQ toggling. CL=3 and BL=4 is assumed and the V_{DDQ} current is excluded.5) $t_{RFC} = t_{RFC(min)}$ "burst refresh", $t_{RFC} = 7.8 \mu s$ "distributed refresh"6) 1.05 mA at $85^\circ C$, 1.00 mA at $60^\circ C$



4.2 AC Characteristics

This chapter lists the AC characteristics.

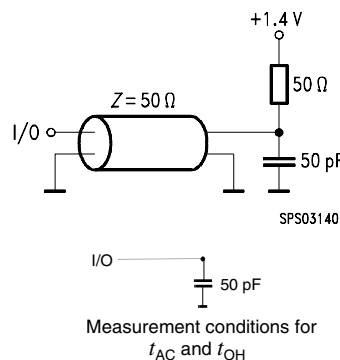
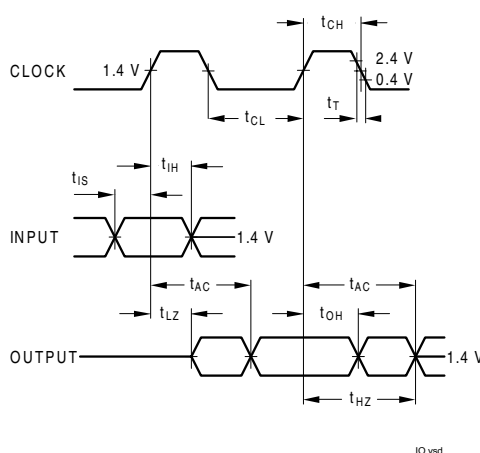
TABLE 13
AC Timing - Absolute Specifications

Parameter	Symbol	−7		−6		Unit	Note ¹⁾²⁾³⁾
		PC143–333		PC166–333			
		Min.	Max.	Min.	Max.		
Clock and Clock Enable							
Clock Frequency	t_{CK}	7 7.5	— —	6 7.5	— —	ns ns	CL3 CL2
Access Time from Clock	t_{AC}	— —	5.4 5.4	— —	5.4 5.4	ns ns	CL3 CL2 3)4)5)
Clock High Pulse Width	t_{CH}	2.5	—	2	—	ns	
Clock Low Pulse Width	t_{CL}	2.5	—	2	—	ns	
Transition time	t_T	0.3	1.2	0.3	1.2	ns	
Setup and Hold Times							
Input Setup Time	t_{IS}	1.5	—	1.5	—	ns	6)
Input Hold Time	t_{IH}	0.8	—	0.8	—	ns	6)
CKE Setup Time	t_{CKS}	1.5	—	1.5	—	ns	6)
CKE Hold Time	t_{CKH}	0.8	—	0.8	—	ns	6)
Mode Register Set-up to Active delay	t_{RSC}	2	—	2	—	t_{CK}	
Power Down Mode Entry Time	t_{SB}	0	7	0	6	ns	
Common Parameters							
Row to Column Delay Time	t_{RCD}	15	—	15	—	ns	7)
Row Precharge Time	t_{RP}	15	—	15	—	ns	7)
Row Active Time	t_{RAS}	37	100k	36	100k	ns	7)
Row Cycle Time	t_{RC}	60	—	60	—	ns	7)
Row Cycle Time during Auto Refresh	t_{RFC}	63	—	60	—	ns	
Activate(a) to Activate(b) Command period	t_{RRD}	14	—	12	—	ns	7)
CAS(a) to CAS(b) Command period	t_{CCD}	1	—	1	—	t_{CK}	
Refresh Cycle							
Refresh Period (8192 cycles)	t_{REF}	–	64	–	64	ms	
Self Refresh Exit Time	t_{SREX}	1	—	1	—	t_{CK}	
Data Out Hold Time	t_{OH}	3	—	2.5	—	ns	3)5)
Read Cycle							
Data Out to Low Impedance Time	t_{LZ}	0	—	0	—	ns	
Data Out to High Impedance Time	t_{HZ}	3	7	3	6	ns	
DQM Data Out Disable Latency	t_{DQZ}	—	2	—	2	t_{CK}	



Parameter	Symbol	−7		−6		Unit	Note ¹⁾²⁾³⁾		
		PC143–333		PC166–333					
		Min.	Max.	Min.	Max.				
Write Cycle									
Last Data Input to Precharge (Write without Auto Precharge)	t_{WR}	14	—	12	—	ns	8)		
Last Data Input to Activate(Write with Auto Precharge)	$t_{DAL(min.)}$					t_{CK}	9)		
DQM Write Mask Latency	t_{DQW}	0	—	0	—	t_{CK}			

- FIGURE 5**
Measurement conditions for t_{AC} and t_{OH}

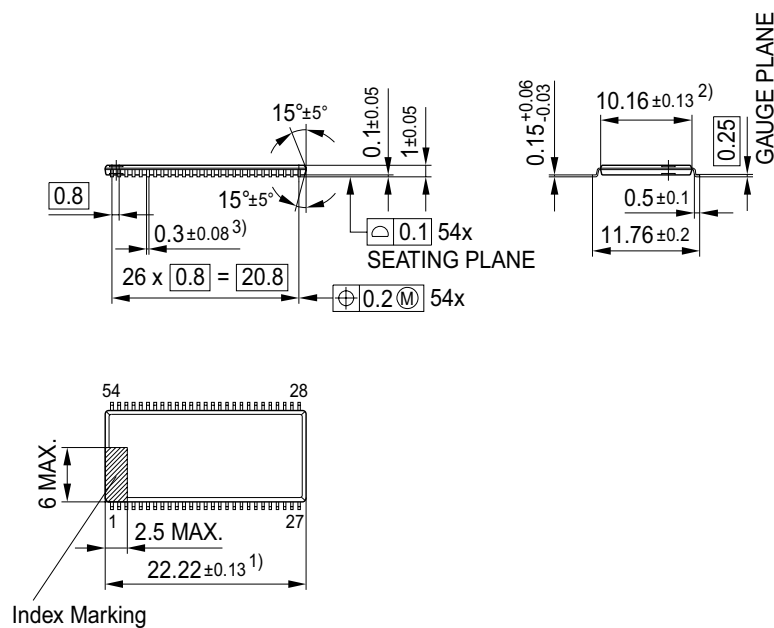




5 Package Outlines

This chapter contains the package outlines of the products.

FIGURE 6
Package Outline P(G)-TSOPII-54 (top view)

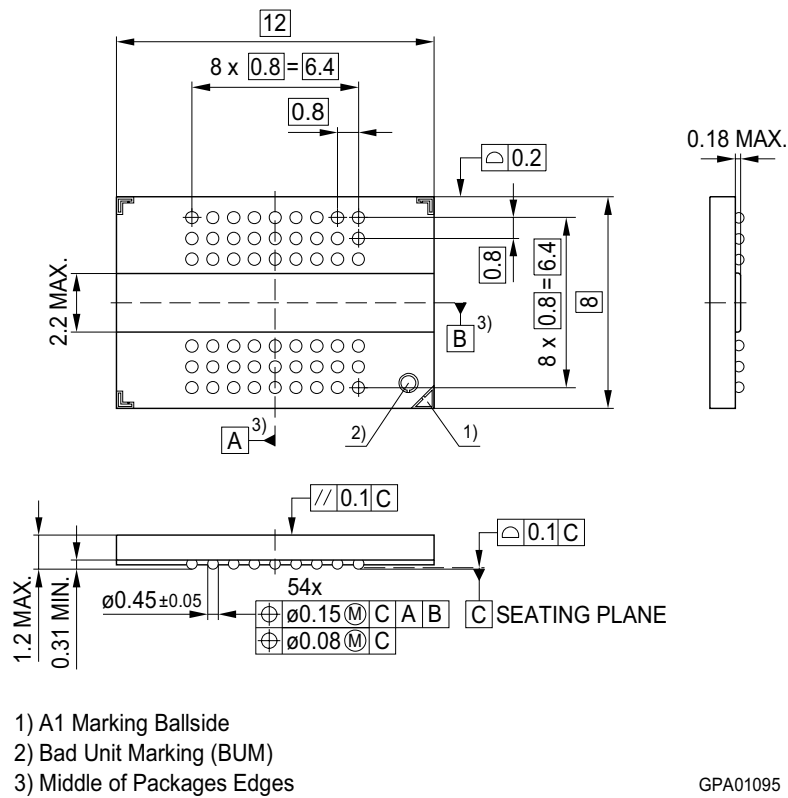


- 1) Does not include plastic or metal protrusion of 0.15 max. per side
2) Does not include plastic protrusion of 0.25 max. per side
3) Does not include dambar protrusion of 0.13 max. per side

GPX01088

Notes

1. Drawing according to ISO 8015
2. Dimensions in mm
3. General tolerances ± 0.15

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256-MBit Synchronous DRAM**FIGURE 7**
Package Outline P(G)-TFBGA-54**Notes**

1. Drawing according to ISO 8015
2. Dimensions in mm
3. General tolerances ± 0.15

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6 Product Nomenclature

For reference the Qimonda SDRAM component nomenclature is enclosed in this chapter.

TABLE 14
Examples for Nomenclature Fields

Example for	Field Number										
	1	2	3	4	5	6	7	8	9	10	11
SDRAM	HYB	39	S	256	80		0	F	F		–6
SDRAM	HYI	39	S	256	16		0	F	E		–7

TABLE 15
Memory Components

Field	Description	Values	Coding
1	Qimonda Component Prefix	HYB	Memory components
		HYI	Memory components, industrial temperature range (–40°C – +85 °C)
2	Interface Voltage [V]	39	3.3 V
3	DRAM Technology	S	Single Data Rate SDRAM
4	Component Density [Mbit]	128	128 Mbit
		256	256 Mbit
		512	512 Mbit
5+6	Number of I/Os	40	×4
		80	×8
		16	×16
7	Product Variations	0 .. 9	look up table
8	Die Revision	C	Third
		D	Fourth
		F	Fifth
9	Package, Lead-Free Status	E	TSOP, lead- and halogen-free
		F	FBGA, lead- and halogen-free
10	Power	–	Standard power product
11	Speed Grade	–6	PC166-333
		–7	PC143-333, PC133-222



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